

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jeng-Shyan LIN</td> <td>10/28/2010</td> </tr> <tr> <td>Dun-Nian YAUNG</td> <td>10/28/2010</td> </tr> <tr> <td>Jen-Cheng LIU</td> <td>10/28/2010</td> </tr> <tr> <td>Hsin-Hui LEE</td> <td>11/03/2010</td> </tr> <tr> <td>Wen-De WANG</td> <td>10/27/2010</td> </tr> <tr> <td>Shu-Ting TSAI</td> <td>10/27/2010</td> </tr> </tbody> </table>		Name	Execution Date	Jeng-Shyan LIN	10/28/2010	Dun-Nian YAUNG	10/28/2010	Jen-Cheng LIU	10/28/2010	Hsin-Hui LEE	11/03/2010	Wen-De WANG	10/27/2010	Shu-Ting TSAI	10/27/2010
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Shu-Ting TSAI	10/27/2010														
RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.														
Street Address:	No. 8, Li-Hsin Rd. 6														
Internal Address:	Science-Based Industrial Park														
City:	Hsin-Chu														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12916789</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12916789										
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CORRESPONDENCE DATA															
Fax Number:	(214)200-0853														
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ATTORNEY DOCKET NUMBER:	24061.1643(TSMC2010-0692)														

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PATENT
REEL: 025466 FRAME: 0509

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- (1) Jeng-Shyan Lin of No. 44, Alley 116, Lane 175, Sec. 1, Datong Rd., East District Tainan City 701, Taiwan, R.O.C.
- (2) Dun-Nian Yaung of 4F, No. 15, Lane 130, Wansheng Street, Wunshan District Taipei City 116, Taiwan, R.O.C.
- (3) Jen-Cheng Liu of 5F, #219, Guan-Dong Road Hsin-Chu City, Taiwan, R.O.C.
- (4) Hsin-Hui Lee of 3F, No. 331-3, Fu-Min Road Kaohsiung, Taiwan, R.O.C.
- (5) Wen-De Wang of No. 17, Jhonghe Village Minsyong Township, Chiayi County 621, Taiwan, R.O.C.
- (6) Shu-Ting Tsai of No. 27, Baoding Street, Sanmin District Kaohsiung City 807, Taiwan, R.O.C.

have invented certain improvements in

SEAL RING STRUCTURE WITH A METAL PAD

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
x filed on November 1, 2010 and assigned application number 12/916,789; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries

Docket No.: 2010-0692 / 24061.1643
Customer No.: 42717

foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jeng-Shyan Lin

Residence Address: No. 44, Alley 116, Lane 175, Sec. 1, Datong Rd., East District
Tainan City 701, Taiwan, R.O.C.

Dated: 10/28/10

Jeng-Shyan Lin
Inventor Signature

Inventor Name: Dun-Nian Yang

Residence Address: 4F, No. 15, Lane 130, Wansheng Street, Wunshan District
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Dated: 10/28/10

Dun-Nian Yang
Inventor Signature

Inventor Name: Jen-Cheng Liu

Residence Address: 5F, #219, Guan-Dong Road
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Dated: 10/28/10

Jen-Cheng Liu
Inventor Signature

Inventor Name: Hsin-Hui Lee
 Residence Address: 3F, No. 331-3, Fu-Min Road
 Kaohsiung, Taiwan, R.O.C.
 Dated: 11/03/10 Hsin Hui Lee
 Inventor Signature

Inventor Name: Wen-De Wang
 Residence Address: No. 17, Jhonghe Village
 Minsyong Township, Chiayi County 621, Taiwan, R.O.C.
 Dated: 10/27/10 Wen-De Wang
 Inventor Signature

Inventor Name: Shu-Ting Tsai
 Residence Address: No. 27, Baoding Street, Sanmin District
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 Dated: 10/27/10 Shu-Ting Tsai
 Inventor Signature
